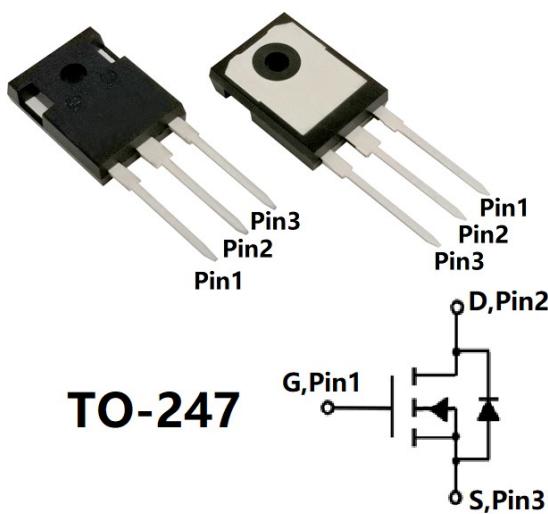




## N-Channel Enhancement Mode Field Effect Transistor



### Product Summary

- $V_{DS}$  100V
- $I_D$  60A
- $R_{DS(on)}$  (at  $V_{GS}=10V$ )  $<17.5$  mohm
- 100% UIS Tested
- 100%  $\nabla V_{DS}$  Tested

### General Description

- Low  $R_{DS(on)}$  & FOM
- Extremely low switching loss
- Excellent stability and uniformity
- Fast switching and soft recovery

### Applications

- Switching converters
- Motor drivers
- Power management

#### ■ Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-source Voltage	$V_{DS}$	100	V
Gate-source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	60	A
		38	
Pulsed Drain Current <sup>A</sup>	$I_{DM}$	300	A
Avalanche energy <sup>B</sup>	$E_{AS}$	81	mJ
Total Power Dissipation <sup>C</sup>	$P_D$	260	W
		104	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

#### ■ Thermal resistance

Parameter	Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient <sup>D</sup>	$R_{\theta JA}$	5	8	°C/W
Thermal Resistance Junction-to-Ambient <sup>D</sup>		30	40	
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.4	0.48	

#### ■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJN60G10B	B1	YJN60G10B	30	360	1800	Tube



# YJN60G10B

## ■ Electrical Characteristics ( $T_j=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Units
<b>Static Parameter</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=100\text{V}, V_{\text{GS}}=0\text{V}$			1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			$\pm 100$	nA
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	2	2.8	4	V
Static Drain-Source On-Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=20\text{A}$		15	17.5	$\text{m}\Omega$
Diode Forward Voltage	$V_{\text{SD}}$	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.3	V
Maximum Body-Diode Continuous Current	$I_{\text{S}}$				45	A
Gate resistance	$R_{\text{G}}$	f= 1 MHz, Open drain		1		$\Omega$
<b>Dynamic Parameters</b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=50\text{V}, V_{\text{GS}}=0\text{V}, f=1\text{MHz}$		1135		pF
Output Capacitance	$C_{\text{oss}}$			399		
Reverse Transfer Capacitance	$C_{\text{rss}}$			18		
<b>Switching Parameters</b>						
Total Gate Charge	$Q_{\text{g}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=25\text{A}$		16		nC
Gate-Source Charge	$Q_{\text{gs}}$			5.6		
Gate-Drain Charge	$Q_{\text{gd}}$			2.4		
Reverse Recovery Charge	$Q_{\text{rr}}$	$I_{\text{F}}=20\text{A}, dI/dt=100\text{A/us}$		42		ns
Reverse Recovery Time	$t_{\text{rr}}$			39.8		
Turn-on Delay Time	$t_{\text{D(on)}}$			39.2		
Turn-on Rise Time	$t_{\text{r}}$	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=50\text{V}, I_{\text{D}}=25\text{A}$ $R_{\text{GEN}}=2.2\Omega$		11		ns
Turn-off Delay Time	$t_{\text{D(off)}}$			53.2		
Turn-off fall Time	$t_{\text{f}}$			15.8		

- A. Repetitive rating; pulse width limited by max. junction temperature.
- B.  $V_{\text{DD}}=50\text{V}, R_{\text{G}}=25\Omega, L=0.5\text{mH}, I_{\text{AS}}=25\text{A}.$
- C.  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- D. The value of  $R_{\text{qJA}}$  is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A = 25^\circ\text{C}$ . The Power dissipation PDSM is based on  $R_{\text{qJA}} \leq 10\text{s}$  and the maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.



## ■ Typical Performance Characteristics

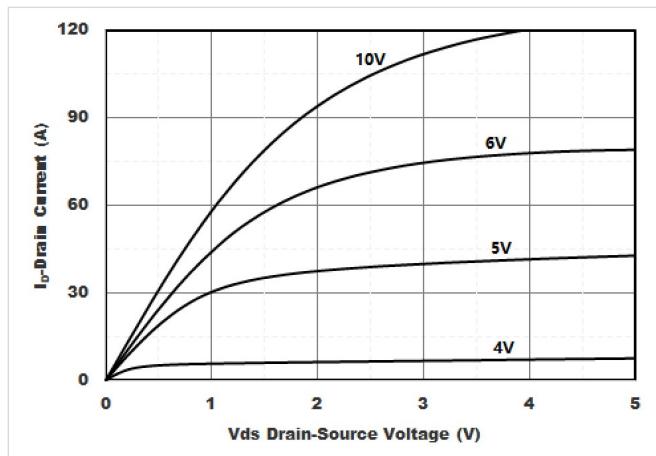


Figure1. Output Characteristics

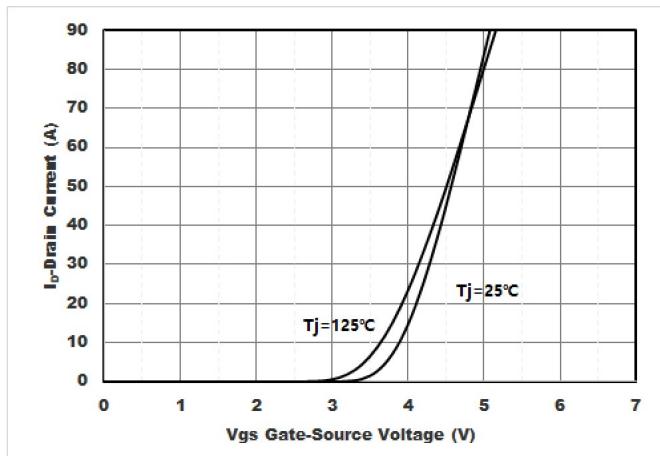


Figure2. Transfer Characteristics

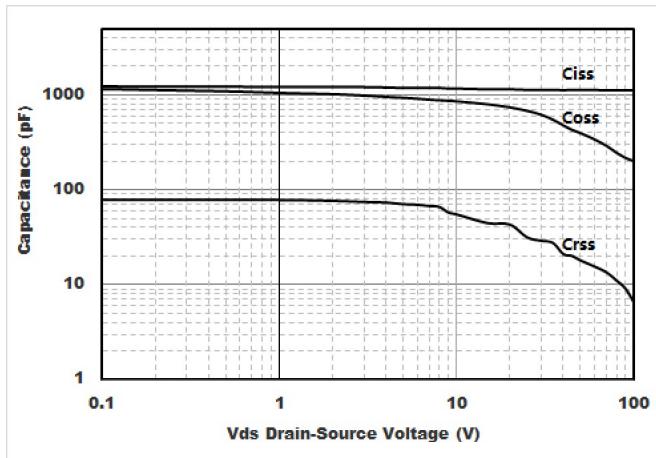


Figure3. Capacitance Characteristics

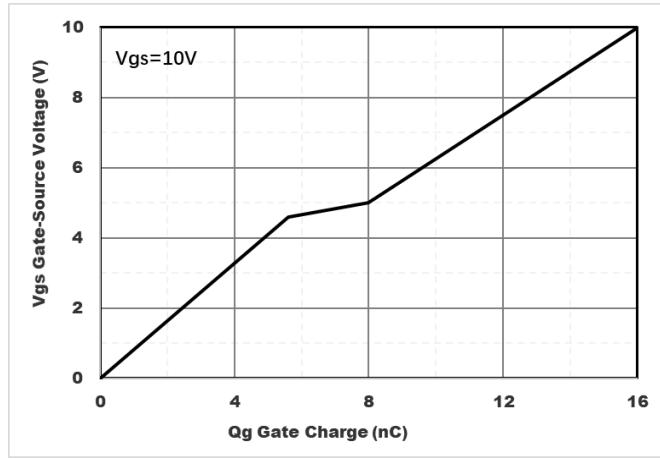


Figure4. Gate Charge

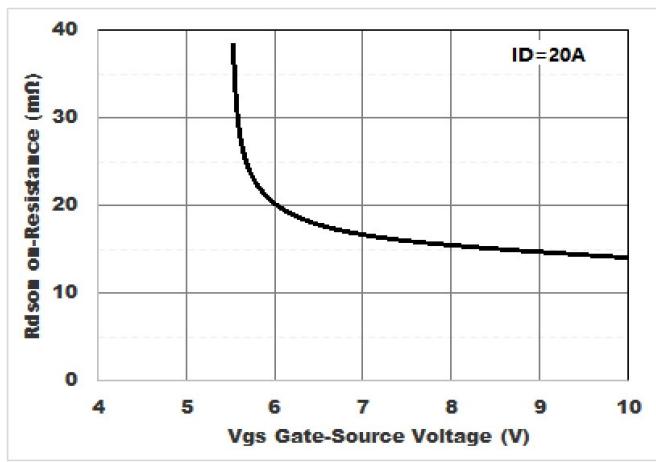


Figure5. : On-Resistance vs. Drain Current and Gate Voltage

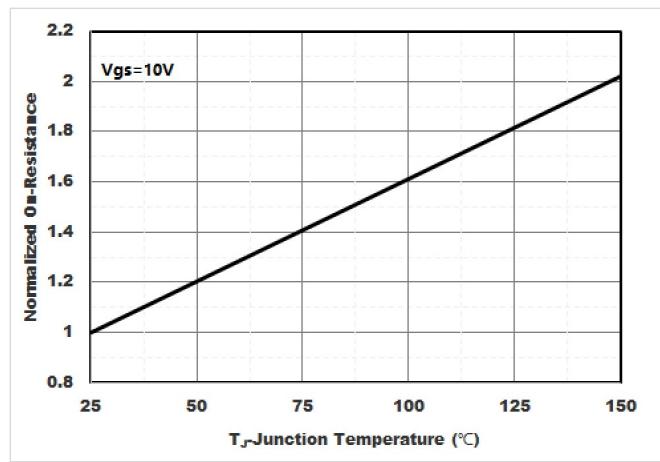


Figure6.Normalized On-Resistance

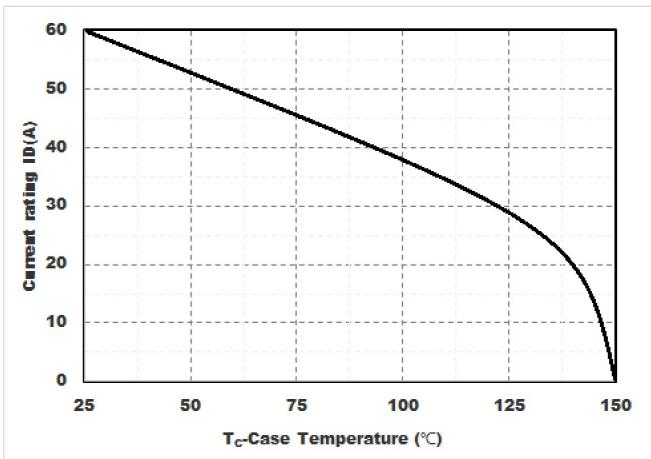


Figure 7. Drain current

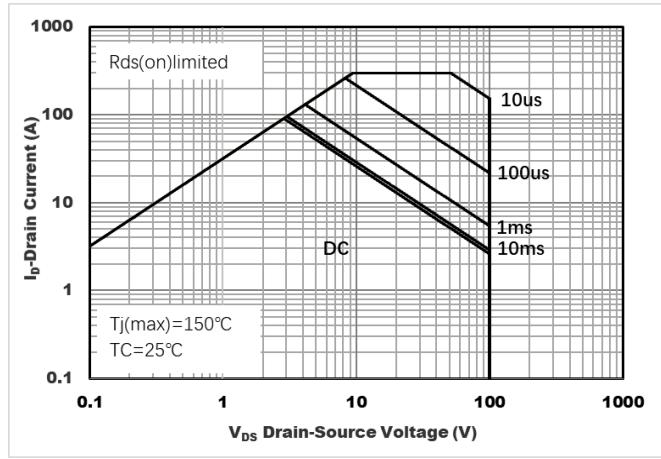


Figure 8. Safe Operation Area

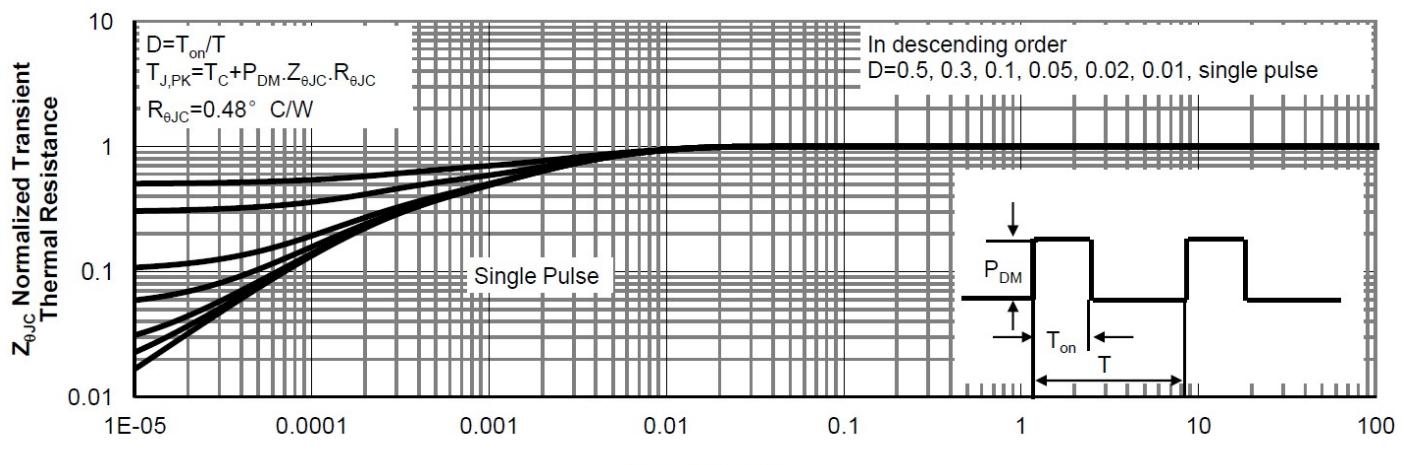
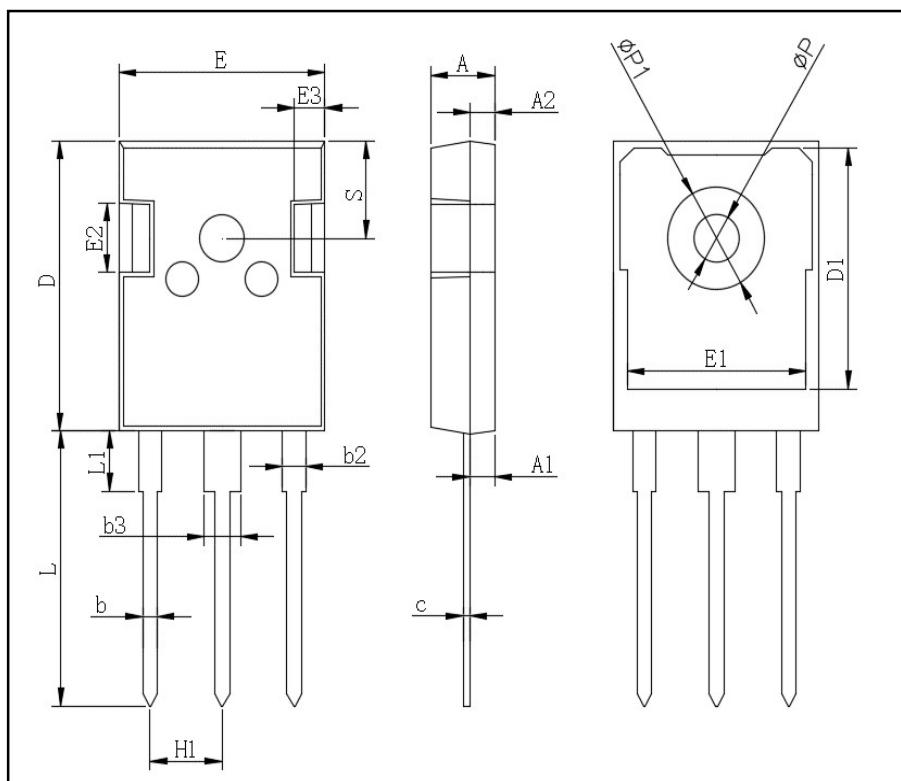


Figure 9. Normalized Maximum Transient thermal impedance



## ■ TO-247 Package Information



TO-247AB		
Dim	Min	Max
A	4.80	5.20
A1	2.21	2.61
A2	1.85	2.15
b	1.0	1.4
b2	1.91	2.21
C	0.5	0.7
D	20.70	21.30
D1	16.25	16.85
E	15.50	16.10
E1	13.0	13.6
E2	4.80	5.20
E3	2.30	2.70
L	19.62	20.22
L1	-	4.30
ΦP	3.40	3.80
ΦP1	-	7.30
S	6.15TYP	
H1	5.44TYP	
b3	2.80	3.20



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